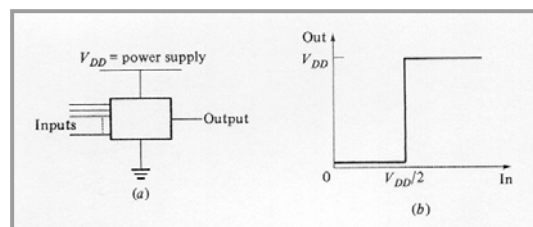


Addendum: Digital Integrated Circuits

ECE 152A – Fall 2006

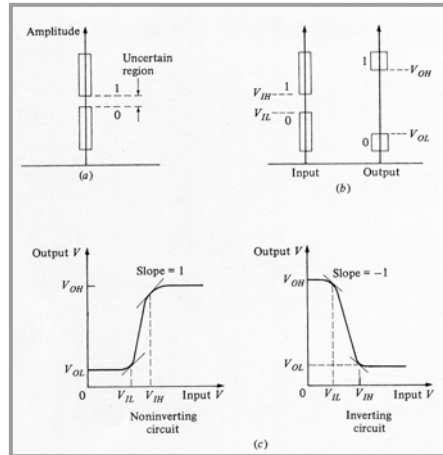
Properties of Digital Integrated Circuits

- The Ideal Digital Circuit



Digital IC Definitions

Amplitude and Voltage Transfer Characteristics



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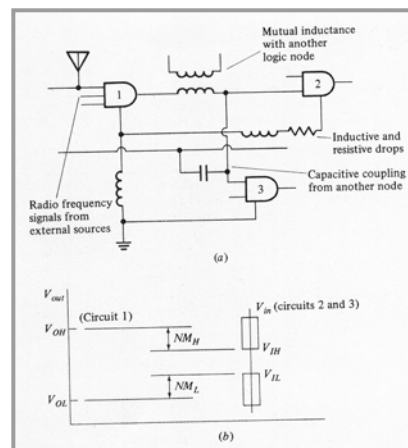
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Digital IC Definitions

Noise Margins

- Sources of noise
- Definition of noise margins



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TTL Electrical Characteristics

- Standard TTL (54/74)

TABLE 7.3
Standard transistor-transistor logic (54/74 TTL):
typical electrical characteristics at $T_A = 25^\circ\text{C}$

| | | | |
|-----------------|-------------|----------------------------|---------|
| V_{OH}/V_{OL} | 3.5 V/0.2 V | Fan-out | 10 |
| V_{IH}/V_{IL} | 1.5 V/0.5 V | Supply volts | + 5.0 V |
| NM_H/NM_L | 2.0 V/0.3 V | Power dissipation per gate | 10 mW |
| Logic swing | 3.3 V | Propagation delay time | 10 ns |

TTL Electrical Characteristics

- Comparison of Standard TTL (74), Schottky Clamped TTL (74S) and Low Power Schottky TTL (74LS)

TABLE 7.4
Transistor-transistor logic: performance characteristics at $T_A = 25^\circ\text{C}$

| | Series 74 | Series 74S | Series 74LS |
|------------------------------------|----------------------------------|----------------------------------|----------------------------------|
| min $V_{OH}/\text{max } V_{OL}$ | 2.4 V/0.4 V | 2.7 V/0.5 V | 2.7 V/0.5 V |
| min $V_{IH}/\text{max } V_{IL}$ | 2.0 V/0.8 V | 2.0 V/0.8 V | 2.0 V/0.8 V |
| min $I_{OH}/\text{min } I_{OL}$ | -0.4 mA/16 mA | -1.0 mA/20 mA | -0.4 mA/8 mA |
| max $I_{IH}/\text{max } I_{IL}$ | 40 $\mu\text{A}/-1.6 \text{ mA}$ | 50 $\mu\text{A}/-2.0 \text{ mA}$ | 20 $\mu\text{A}/-0.4 \text{ mA}$ |
| Typical propagation delay time | 10 ns | 3 ns | 10 ns |
| Typical power dissipation per gate | 10 mW | 20 mW | 2 mW |

TTL vs. CMOS

■ Comparison of Electrical Characteristics

TABLE 3.2
Bipolar and CMOS logic performance characteristics ($T_A = 25^\circ\text{C}$)

| Parameter | Series | | | | |
|---|---------|-------------------|-------------------|-------------------|-------------------|
| | 74LS | 74HC | 74HCT | 74AC | 74ACT |
| min $V_{OH}/\text{max } V_{OL}$: | | | | | |
| CMOS load | 2.7/0.5 | 4.4/0.1 | 4.4/0.1 | 4.4/0.1 | 4.4/0.1 |
| TTL load | 2.7/0.5 | 4.0/0.3 | 4.0/0.3 | 3.9/0.3 | 3.9/0.3 |
| min $V_{IH}/\text{max } V_{IL}$ | 2.0/0.8 | 3.1/0.9 | 2.0/0.8 | 3.1/1.3 | 2.0/0.8 |
| min $I_{OH}/\text{min } I_{OL}$, mA | -0.4/8 | ± 4 | ± 4 | ± 24 | ± 24 |
| max $I_{IH}/\text{max } I_{IL}$, μA | 20/-400 | ± 0.1 | ± 0.1 | ± 0.1 | ± 0.1 |
| Typical t_p , ns | 10 | 10 | 10 | 5 | 5 |
| Typical dc P_D/gate | 2 mW | 2.5 μW | 2.5 μW | 2.5 μW | 2.5 μW |

For Series 74LS: $V_{CC} = 5\text{ V}$ $C_L = 15\text{ pF}$
 For CMOS Series: $V_{CC} = 4.5\text{ V}$ $C_L = 50\text{ pF}$

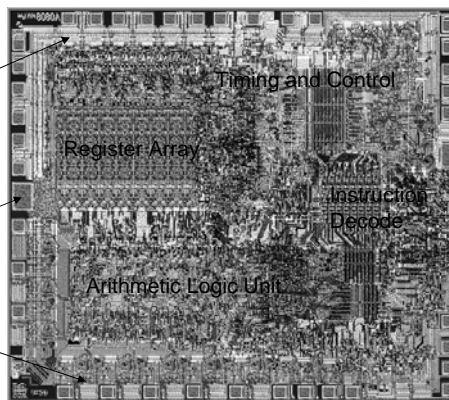
VLSI Circuits

■ Intel 8080

Address Bus Drivers

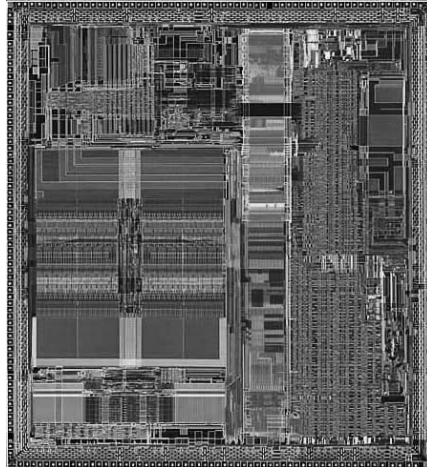
Ground Pad

Bidirectional Data Bus
Driver/Receivers



VLSI Circuits

- Intel Pentium



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Power Dissipation in CMOS Circuits

- There are two components that establish the amount of power dissipation in a CMOS circuit
 - Static Power Dissipation
 - Constant current
 - Dynamic Power Dissipation
 - Currents attributed to switching

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Power Dissipation in CMOS Circuits

- **Static dissipation**
 - Reverse bias leakage current
 - Parasitic diode between diffusion regions and substrate
 - Subthreshold leakage current in static CMOS circuits
 - pMOS and/or nMOS devices not completely turned off
 - Constant current in non static CMOS circuits
 - Psuedo-nMOS, I/O, Analog circuits, etc.

Power Dissipation in CMOS Circuits

- **Dynamic dissipation**
 - Switching transient current
 - Occurs on transition from 1 to 0 (or 0 to 1)
 - Results in short current pulse from V_{DD} to V_{SS}
 - Referred to as "short-circuit dissipation"
 - Dependent on rise and fall times
 - Slow rise and fall times increase short circuit current
 - Critical in I/O buffer design
 - Dominant component of dynamic power with little or no capacitive loading

Power Dissipation in CMOS Circuits

- Dynamic dissipation (cont)
 - Charging and discharging of load capacitances
 - As capacitive loading is increased, the charging and discharging currents begin to dominate the current drawn from the power supplies

$$P_d = \frac{1}{t_p} \int_0^{t_p/2} i_n(t) V_{out} dt + \frac{1}{t_p} \int_{t_p/2}^{t_p} i_p(t) (V_{DD} - V_{out}) dt,$$

where

i_n = n-device transient current

i_p = p-device transient current.

Power Dissipation in CMOS Circuits

- Dynamic dissipation (cont)
 - Charging and discharging of load capacitances

For a step input and with $i_n(t) = C_L dV_{out}/dt$ (C_L = load capacitance)

$$P_d = \frac{C_L}{t_p} \int_0^{V_{DD}} V_{out} dV_{out} + \frac{C_L}{t_p} \int_{V_{DD}}^0 (V_{DD} - V_{out}) d(V_{DD} - V_{out})$$

$$= \frac{C_L V_{DD}^2}{t_p}$$

with $f_p = 1/t_p$,
resulting in

$$P_d = C_L V_{DD}^2 f_p$$

Power Dissipation in CMOS Circuits

- Dynamic short-circuit vs. capacitive current

